

Electronic Acknowledgement Receipt

EFS ID:	9289642
Application Number:	10055560
International Application Number:	
Confirmation Number:	6103
Title of Invention:	INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND METHOD OF MANUFACTURING THE SAME
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Patricia Balero
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0058
Receipt Date:	24-JAN-2011
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Time Stamp:	13:59:20
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1		DolceraInformationDisclosureStatement-085027-0058.pdf	166992 8cb98af064570215a0f1c02b61d453c251fbfbc	yes	5

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	3	
	Information Disclosure Statement (IDS) Filed (SB/08)		4	5	
Warnings:					
Information:					
2	Foreign Reference	TW385509_FRN00123.pdf	6828863	no	53
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3	Foreign Reference	TW417265_FRN00124.pdf	2756476	no	26
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4	Foreign Reference	TW449894_FRN00122.pdf	2918238	no	28
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	Transmittal Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	4	
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6		TS-5InformationDisclosureStatement-085027-0058.pdf	159434	yes	4
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7		OrphanInformationDisclosureStatement-085027-0058.pdf	188724 70b26b674c7620f68e51a5c8ef5b06d7fd13b5c7	yes	5
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8	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 072127b124142b87d48b36305577e00d7f281092	no	4
Warnings:					
Information:					
9	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109 daa31204b1d9d203a708a79ef619df4655068f74	no	9
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10	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a340bcb7c9b1547370da4bc4129a0cd8aae74	no	7
Warnings:					
Information:					
11	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 789f5c75db4f5367e2064f35e1853c2a9776ebb5	no	6
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12	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6ea9c2af4c3f93c0d5e8d84fcc64bb8318ee28a	no	5
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13	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f30badcc448865be25da92121b117fce267a05	no	7
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14	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794	no	8
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15	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090	no	4
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22	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325	no	2
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27	NPL Documents	20_PDF_MALONEY_Novel_clamp_circuits_for_IC_power_supply_protection_pdf.pdf	191082 d68b46b342e836f0eda7955b62f7276a63e41cd7	no	12
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33	NPL Documents	26_PDF_MEGICA_Brochure_letters_01_28_04_pdf.pdf	888383 aec89db5e67eb17d33ea9f52144d8fbc181fd9a	no	3
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34	NPL Documents	27_PDF_LIN_Post_Passivation_Technology_Presentation_for_TSMC_Tech_Symposium_2003__pdf.pdf	1277639 20556e2754a2807cec285bcc5d87f24d52717e89	no	32
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35	NPL Documents	28_PDF_LIN_A_New_IC_Interconnection_Scheme_and_Design_pdf.pdf	116206 e1e1d6bb5cdf0007c76b6677a40a8a47106eecb8	no	4
Warnings:					
Information:					
Total Files Size (in bytes):			53953303		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					